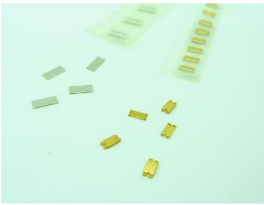
SMD GROUNDING PLATE

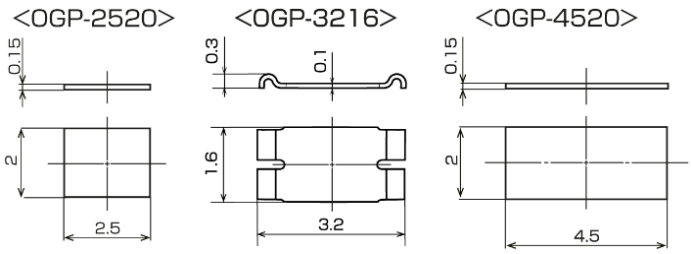
Kitagawa series: OGP

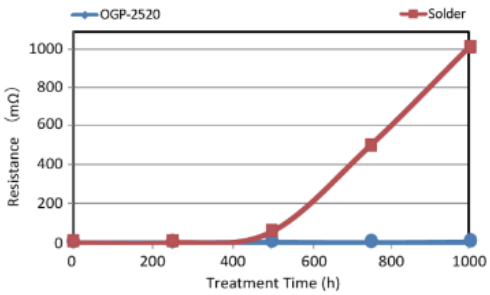


- Solves contact failures caused by solder flux.
- Configuration ensures reliable contact.
- Eliminates continuity failure caused by pattern scraping between PCB and pogo pins/metal plate.
- Gold plated OGP-3216 can be used as partial gold plating on PCBs.

Application Examples | Reel Quantities

Part Number	Material	Height	Temperature Range
OGP-2520	Brass (Sn reflow plating)	0.15mm	-40 to +85°C
OGP-3216	Brass (Au plating)	0.3mm	-40 to +85°C
OGP-4520	Brass (Sn reflow plating)	0.15mm	-40 to +85°C





Treatment condition: 125℃